

LABORATORY WORK SHEET

Name of the Student MADKI SAL CHARAN Class CSM-C Semester IST Course Code: AMEDO2 Course Name Manufacturing Plactice Plactice reduced the Course Faculty Mx · V · Makidhar reduced.													
Course Code Am f	F.D.O.2 Cou	rse Name Manu	facti	uing	2	3	9	5	1	A	66	F	2
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Exercise Number :							-	Da	te :i	01	Dec	emb	W. 31

DAY TO DAY EVALUATION:

Marks	Aim /	Algorithm / Procedure	Source Code	Program Execution	Viva -	4000	
	Preparation	Performance in the Lab	Calculations and Graphs	Results and Error Analysis	Voce	Total	
Max. Marks	4	4	4	4	4	20	
Obtained	1	H	11	11	4	90	

Signature of Faculty

START WRITING FROM HERE:

Aim : solidering and de-solidering at the electronic Components.

Materials required: Take any circuit board (for soldering)

Tools required: 1.30 Volts Soldering Iron

2. Soldering Iron Stand.

3. Flux

4. Itad

5. Solder wik.

seguence of operations:

- a) Wire cutting.
- b) Wire Flux
- () soldering.
- d) De-Soldering.

Procedure: soldering:

- -) All the parts must be clean and free from dut and grease.
- -> Try to secure the work firmly.
- -> "Tin" the irontip with a small amount of Solder. Do this immediately with new tip being used for first time.
- oden the tip of the not soldering iron or damp sponge
- fresh, solder to the cleansed tip.
- -> Heat all parts of the joint with the iron for under a Second or so.

- only, to form an adequate joint.
- -) Remove and tun non safety to its stand.
- The only takes two lon three selond at must, to solder the average printed circuit board (PCB)
- -> Do not move pouts until the solder has.

Desoldering:

- -> Apply the flux at de-solder area.
- -> Heat up the solder at desolder point with ison.
- -> keep desolder wick or wire on desolder point or and slide the iron up on desolder point to bring.

 mast of the Solder away from joint.
- to remove their pins from the pin holders while they are not heat.
- -> After removed clean with brush and cleansing. 501.

Precautions:

- -) wiring must be ensured in accordance with electrical regulation and standard.
- Avoid direct Contact of wires while testing.
- -> use testa, multi-meta, while testing circuit.
- After main switch offenly the connection has to be rectified.
- -> Always return the Soldering from to its.

 Sandwise not in use.

Result:

The preparation of desolduing of specified electronic components from printed execute board sofely and soldering soldered component in its.